Docket: CS 99 - 065 S/N: 09/442,499 JUN 20 2003 %

JUN 23 2003 TC 1700

GP1763

To:

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Commissioner of Patents and Trademarks

Washington, D.C. 20231

From:

George O. Saile, Reg. No. 19,572

20 McIntosh Drive

Poughkeepsie, N.Y. 12603

Subject:

Serial No.: 09/442,499

Inventor: Ho

Title: Plasma Etch Method For Forming Plasma Etched Silicon

Layer

Group Art Unit: 1763

Examiner: Goudreau, G. A.

6/18/03

Filed: 11/18/99

Attorney Docket: CS 99 - 065

RESPONSE TO PATENT OFFICE ACTION

Dear Sir:

In response to the Final office action dated 05/20/03, please

consider the following remarks:

## **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:

Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on \_\_\_\_\_\_, 2003.

Signature/Date

Stephen B. Ackerman

Reg. No. 37,761